

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

Entry of the amendments is proper under 37 CFR §1.116 since the amendments: (a) place the application in condition for allowance (for the reasons discussed herein); (b) do not raise any new issue requiring further search and/or consideration (since the amendments amplify issues previously discussed throughout prosecution); (c) satisfy a requirement of form asserted in the previous Office Action; (d) do not present any additional claims without canceling a corresponding number of finally rejected claims; and (e) place the application in better form for appeal, should an appeal be necessary. The amendments are necessary and were not earlier presented because they are made in response to arguments raised in the final rejection. Entry of the amendments is thus respectfully requested.

I. THE SPECIFICATION SATISFIES ALL FORMAL REQUIREMENTS

The Office Action objects to the specification because reference no. "14" should be "12" on page 12, line 15 of the specification. The Examiner is directed to the Amendment filed November 20, 2002 in which the Specification has been amended to correct the reference number from 14 to 12. Withdrawal of the objection to the specification is respectfully requested.

II. THE CLAIMS DEFINE ALLOWABLE SUBJECT MATTER

The Office Action rejects claims 1, 3-10, 12, 14-19 and 21-22 under 35 U.S.C. §102(b) as anticipated by U.S. Patent No. 5,677,575 to Maeta et al.; claims 1-10, 12-19, 21 and 22 under 35 U.S.C. §102(e) as anticipated by U.S. Patent No. 5,804,882 to Tsukagoshi et al.; and claims 2 and 3 are rejected under 35 U.S.C. §103(a) as unpatentable over Maeta in view of Japanese Patent 07,169,795 to Oda. These rejections are respectfully traversed.

None of the applied art discloses a film formed with a lower adhesion to said adhesive than a base material of said substrate, and said film is broader than each of said leads at their portions opposed to said electrodes, as claimed in claim 1, and similarly claimed in claim 12.

In contrast, the applied art discloses that two or more films are formed. Specifically, Tsukekagoshi discloses spacer elements 6 which are formed on a side of the substrate 4 and are formed of a metal. That is, in figure 1 of Tsukagoshi, there is only one spacer element 6 shown to be formed on the substrate 4, but in fact, a plurality of spacer elements 6 are formed. See column 4, lines 62-64.

Similarly, Maeta discloses in figure 1 and 2, a circuit board 1, a semiconductor chip 2, a flat type external connecting terminal 4 and a mold resin layer 5. Also, disclose by Maeta is a wiring circuit 1a including a connecting portion formed on a first main surface of the circuit board 1. The circuit wiring layer 1a extrudes from the surface of the circuit board 1 by approximately 35 $\mu$ m. Thus, the circuit wiring 1a prevents the ceiling resin from being filled into the space.

Thus, in accordance with the techniques disclosed in the applied art, since the two or more films do not have an integrated surface, on the film surfaces, holes and voids in the adhesive do not become easily dispersed.

However, according to the present invention, said film is broader than each of said leads at their portions opposed to said electrodes, as claimed in claim 1 and claimed in claim 12. Thus, in accordance with the present invention, on the broad film surface, holes and voids in the adhesive become easily dispersed. No such feature is taught or disclosed in the applied art.

For at least the reasons discussed above, it is respectfully submitted that claims 1 and 12 are distinguishable over the applied art. Claims 2-10, 13-19 and 21-22, which depend from claims 1 and 12, are likewise distinguishable over the applied art for at least the reasons

discussed above as well as for the additional features they recite. Withdrawal of the rejections under 35 U.S.C. §102 and §103 is respectfully requested.


III. CONCLUSION

In view of the foregoing amendments and remarks, Applicant submit that this application is in condition for allowance. Favorable reconsideration and prompt allowance of are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

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Respectfully submitted,

  
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JAO:KMM/tam

Attachments:  
Appendix  
Petition for Extension of Time

Date: June 26, 2002

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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
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## APPENDIX

## Changes to claims:

1. (Twice Amended) A method of manufacture of a semiconductor device, comprising the steps of:

providing an adhesive between a surface of a semiconductor chip having a plurality of electrodes on which said electrodes are provided and a surface of a substrate having a plurality of leads formed on which said leads are formed;

positioning at least one of said plurality of electrodes to oppose at least one of said plurality of leads; and

applying pressure in a direction such as to make a gap between said semiconductor chip and said substrate narrower;

wherein on the surface of said substrate on which said leads are formed, in a region being at least part of a region of adherence of said semiconductor chip, a film is formed with a lower adhesion to said adhesive than a base material of said substrate, ~~the film formed in such a shape as to avoid the electrodes~~ and said film is broader than each of said leads at their portions opposed to said electrodes.

12. (Twice Amended) A semiconductor device comprising:

a semiconductor chip having a plurality of electrodes;

a substrate on which is formed a plurality of leads; and

an adhesive provided between a surface of said semiconductor chip on which said electrodes are formed and a surface of said substrate on which said leads are formed, and adhering said semiconductor chip and said substrate,

wherein at least one of said plurality of electrodes and at least one of said plurality of leads are electrically connected; and

wherein on said substrate in a region including at least a part of a region opposing said semiconductor chip, a film is formed with a lower adhesion to said adhesive than a base material of said substrate, ~~the film formed in such a shape as to avoid the electrodes~~ and said film is broader than each of said leads at their portions opposed to said electrodes.